

Title (en)
DEVICE AND METHOD FOR THE PLANAR CONNECTION OF TWO WAFERS FOR A THIN-GRINDING AND SEPARATION PROCESS OF A WAFER PRODUCT

Title (de)
VORRICHTUNG UND VERFAHREN ZUM PLANEN VERBINDEN ZWEIER WAFER FÜR EIN DÜNNSCHLEIFEN UND EIN TRENNEN EINES PRODUKT-WAFERS

Title (fr)
DISPOSITIF ET PROCEDE POUR LA LIAISON PLANE DE DEUX PLAQUETTES POUR UN MEULAGE FIN ET UNE SEPARATION D'UNE PLAQUETTE-PRODUIT

Publication
EP 1320873 A1 20030625 (DE)

Application
EP 01982138 A 20010926

Priority
• DE 0103683 W 20010926
• DE 10048881 A 20000929

Abstract (en)
[origin: DE10048881A1] A device for planar connection of two wafers (1,2) together, includes a vacuum chamber (3), a chuck (4), a vacuum chamber cover (18) and a vacuum retaining device (19) for a wafer (1) which is arranged on the vacuum chamber cover such that the product wafer is arranged surface-congruently over the carrier wafer (2) and before joining of the product wafer and the carrier wafer, a spacing (a) is provided between them, such that the spacing is arranged in the vacuum chamber (3).

IPC 1-7
H01L 21/00

IPC 8 full level
H01L 21/00 (2006.01); **H01L 21/683** (2006.01)

CPC (source: EP US)
H01L 21/67092 (2013.01 - EP US); **H01L 21/67132** (2013.01 - EP US); **H01L 21/6838** (2013.01 - EP US)

Citation (search report)
See references of WO 0227764A1

Designated contracting state (EPC)
AT BE CH CY DE FR GB IT LI

DOCDB simple family (publication)
DE 10048881 A1 20020307; EP 1320873 A1 20030625; US 2003173017 A1 20030918; US 2006032587 A1 20060216; US 6972069 B2 20051206; WO 0227764 A1 20020404

DOCDB simple family (application)
DE 10048881 A 20000929; DE 0103683 W 20010926; EP 01982138 A 20010926; US 25247705 A 20051018; US 40387703 A 20030331